



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-29
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HTUI*EDS536V	A	SHENZHEN B/E	2015-06-29
Amount	UoM	Unit type	ST ECOPACK Grade	
1900	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 16.15, 4.5	3	THROUGH HOLE	
Comment	Package: TO 220 ISOL FULL PACK 0.5 AB, MD valid for CP:FERD40U50CFP.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HTU1*ED5536V					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	7.790	mg	supplier	die	Silicon (Si)	7440-21-3		7.547	mg	968806	3972
				supplier	metallization	Aluminium (Al)	7429-90-5		0.098	mg	12580	52
				supplier	Passivation	Silicon Oxide	7631-86-9		0.043	mg	5520	23
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.006	mg	770	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.075	mg	9628	39
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.004	mg	513	2
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.017	mg	2182	9
Leadframe	Copper & its alloys	614.126	mg	supplier	alloy	Copper (Cu)	7440-50-8		604.469	mg	984275	318142
				supplier	alloy	Iron (Fe)	7439-89-6		0.278	mg	453	146
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.508	mg	827	267
				supplier	metallization	Nickel (Ni)	7440-02-0		8.816	mg	14355	4640
				supplier	metallization	Phosphorus (P)	12185-10-3		0.055	mg	90	29
Soft solder	Solder	9.756	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	9.317	mg	955002	4904
				supplier	solder	Silver (Ag)	7440-22-4		0.244	mg	25010	128
				supplier	solder	Tin (Sn)	7440-31-5		0.195	mg	19988	103
Bonding wires	Other inorganic materials	12.039	mg	supplier	wire	Aluminium (Al)	7429-90-5		12.039	mg	1000000	6336
Encapsulation	Other Organic Materials	1250.423	mg	supplier	mold compound	Quartz	14808-60-7		875.296	mg	700000	460682
				supplier	mold compound	Silica, vitreous	60676-86-0		93.782	mg	75000	49359
				supplier	mold compound	Epoxy resin	25068-38-6		175.059	mg	140000	92136
				supplier	mold compound	phenol resin	29690-82-2		87.530	mg	70000	46068
				supplier	mold compound	metal hydroxide	Proprietary		12.504	mg	10000	6581
				supplier	mold compound	carbon black	1333-86-4		6.252	mg	5000	3291
connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087